

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 08-269417

(43)Date of publication of application : 15.10.1996

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(51)Int.Cl. C09J123/20  
C09J157/02  
C09J193/00  
C09J201/00

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(21)Application number : 07-071632

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(22)Date of filing : 29.03.1995

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**(54) HOT MELT ADHESIVE COMPOSITION****(57)Abstract:**

PURPOSE: To obtain a hot melt adhesive having a long open time, does not cause a moisture-permeable olefin resin film to undergo exudation and has a low melt viscosity.

CONSTITUTION: This composition comprises 100 pts.wt. butene-1 homopolymer and/or butene-1 copolymer, 40-300 pts.wt. tackifying resin, and 10-100 pts.wt. unsaturated hydrocarbon oligomer having a flow point of -80 to 30° C and desirably having 4-14 carbon atoms.

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**LEGAL STATUS**

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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